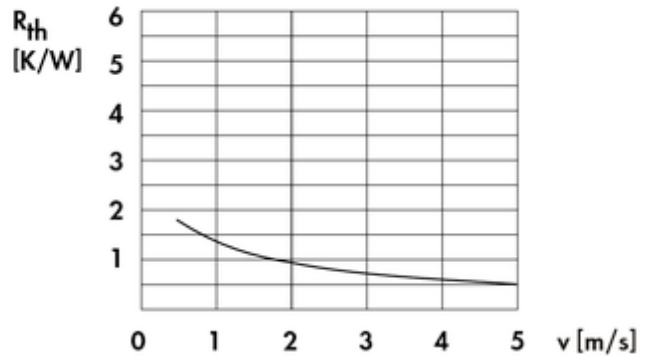
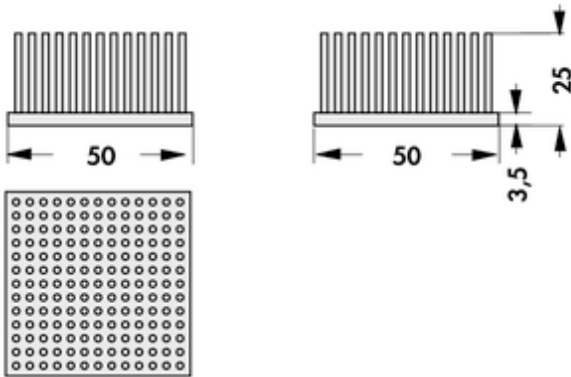
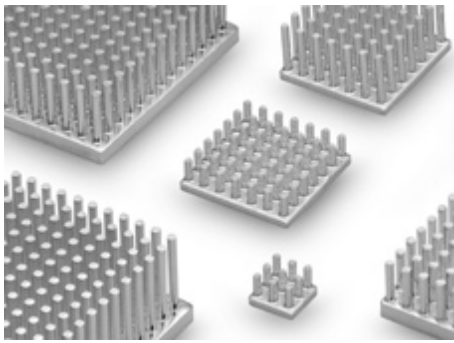


Pin heatsinks / **ICK S 50 x 50 x 25**



50 x 50 x 25 mm, pin heatsinks quadratic

Parameters of article ICK S 50 x 50 x 25

Bauform	Rechteck
R_{th} [K/W]	2.4
dissipation loss [W]	31.2
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	50
height [mm]	25
plate thickness [mm]	3.5
weight [g]	49
length on stock [mm]	50

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 50 x 50**

Thermally conductive foil both sides adhesive / **WLFT 405 50 x 50**